ALPHA & OMEGA SEMICONDUCTOR

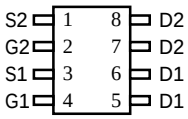
AO4625
Complementary Enhancement Mode Field Effect Transistor

General Description

The AO4625 uses advanced trench technology MOSFETs to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used in power inverters, and other applications.*Standard Product AO4625 is Pb-free (meets ROHS & Sony 259 specifications). AO4625L is a Green Product ordering option. AO4625 and AO4625L are electrically identical.*

Features

n-channel	p-channel
V_{DS} (V) = 30V	-30V
I_D = 6.9A (V_{GS}=10V)	-5.4A (V_{GS} = -10V)
$R_{DS(ON)}$	$R_{DS(ON)}$
< 28mΩ (V_{GS}=10V)	< 45mΩ (V_{GS} = -10V)
< 42mΩ (V_{GS}=4.5V)	< 75mΩ (V_{GS} = -4.5V)



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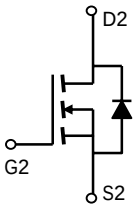
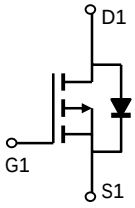


n-channel



p-channel

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Max n-channel	Max p-channel	Units
Drain-Source Voltage		V_{DS}	30	-30	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current [A]	T_A=25°C	I_D	6.9	-5.4	A
	T_A=70°C		5.8	-4.6	
Pulsed Drain Current [B]		I_{DM}	30	-20	
Power Dissipation	T_A=25°C	P_D	2	2	W
	T_A=70°C		1.44	1.44	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	-55 to 150	°C

Thermal Characteristics: n-channel and p-channel

Parameter		Symbol	Device	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	n-ch	48	62.5	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		n-ch	74	110	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	n-ch	35	40	°C/W
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	p-ch	48	62.5	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		p-ch	74	110	°C/W
Maximum Junction-to-Lead [C]	Steady-State	$R_{\theta JL}$	p-ch	35	40	°C/W

N-CHANNEL: Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=24V, V_{GS}=0V		0.004	1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1	1.86	3	V
$I_{D(ON)}$	On state drain current	V_{GS}=4.5V, V_{DS}=5V	30			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=6.9A		22.5	28	mΩ
		T_J=125°C		31.3	38	
		V_{GS}=4.5V, I_D=5.0A		34.5	42	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=6.9A	10	15.4		S
V_{SD}	Diode Forward Voltage	I_S=1A		0.76	1	V
I_S	Maximum Body-Diode Continuous Current				3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		680	820	pF
C_{oss}	Output Capacitance			102		pF
C_{rss}	Reverse Transfer Capacitance			77		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		3	4.5	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=15V, I_D=6.9A		13.84	17	nC
Q_g(4.5V)	Total Gate Charge			6.74	8.1	nC
Q_{gs}	Gate Source Charge			1.82		nC
Q_{gd}	Gate Drain Charge			3.2		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=15V, R_L=2.2Ω, R_{GEN}=3Ω		4.6		ns
t_r	Turn-On Rise Time			4.1		ns
$t_{D(off)}$	Turn-Off DelayTime			20.6		ns
t_f	Turn-Off Fall Time			5.2		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=6.9A, dI/dt=100A/µs		16.5	20	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=6.9A, dI/dt=100A/µs		7.8		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in ^{2} FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using 80 µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in ^{2} FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

Rev 0: Apr. 2006

N-CHANNEL: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

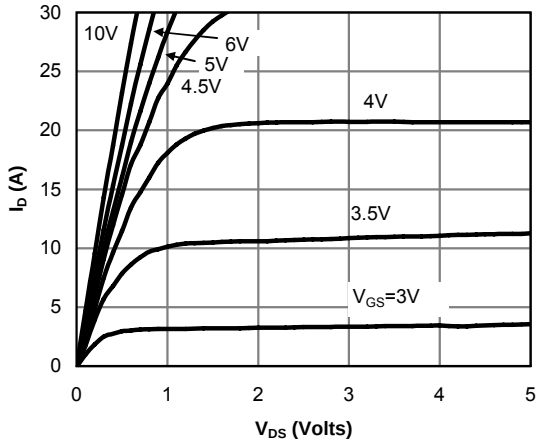


Fig 1: On-Region Characteristics

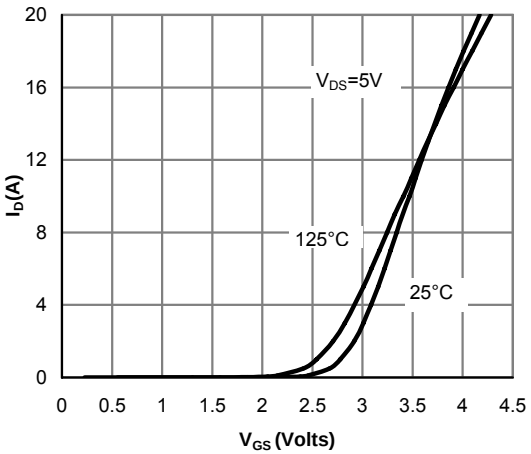


Figure 2: Transfer Characteristics

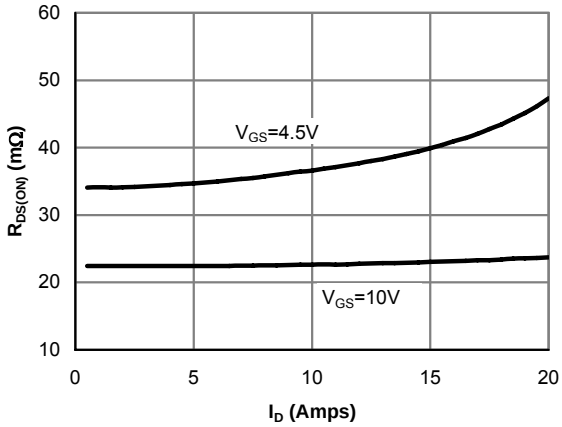


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

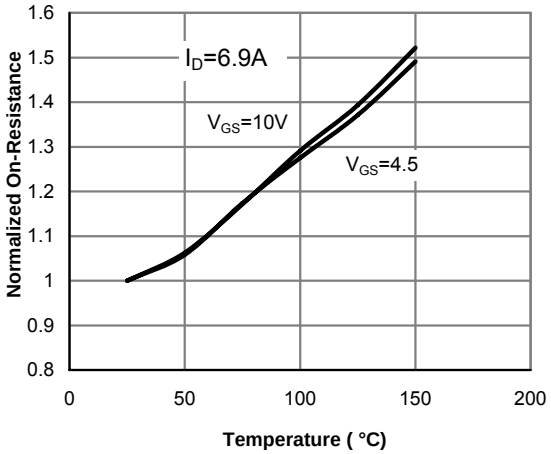


Figure 4: On-Resistance vs. Junction Temperature

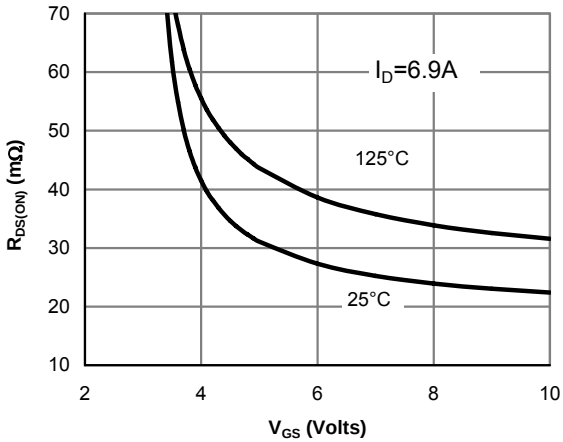


Figure 5: On-Resistance vs. Gate-Source Voltage

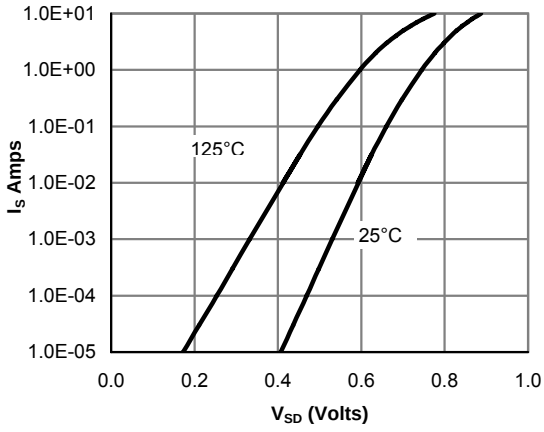


Figure 6: Body diode characteristics

N-CHANNEL: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

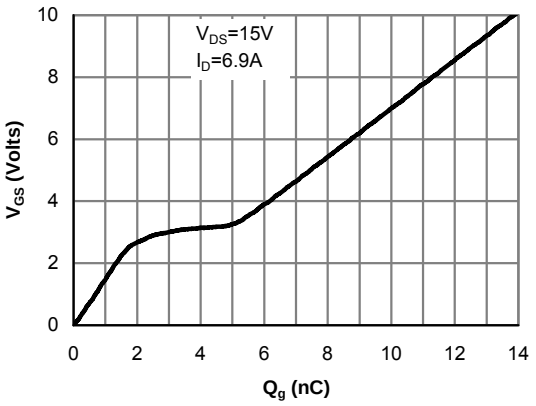


Figure 7: Gate-Charge characteristics

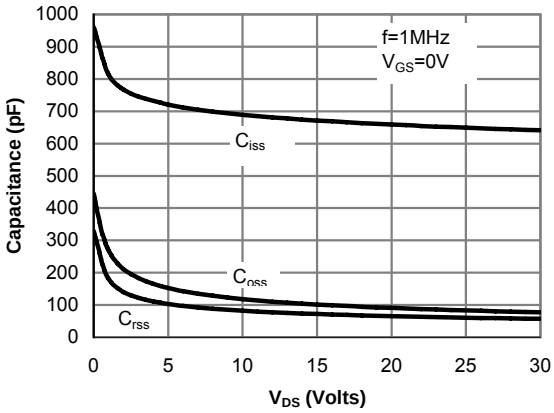


Figure 8: Capacitance Characteristics

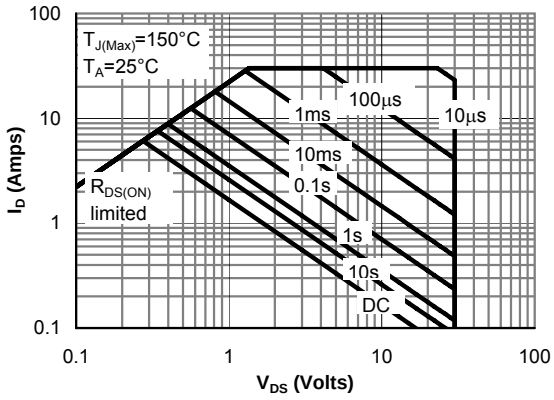


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

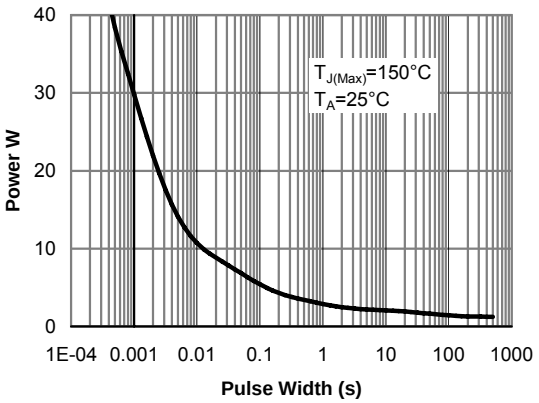


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

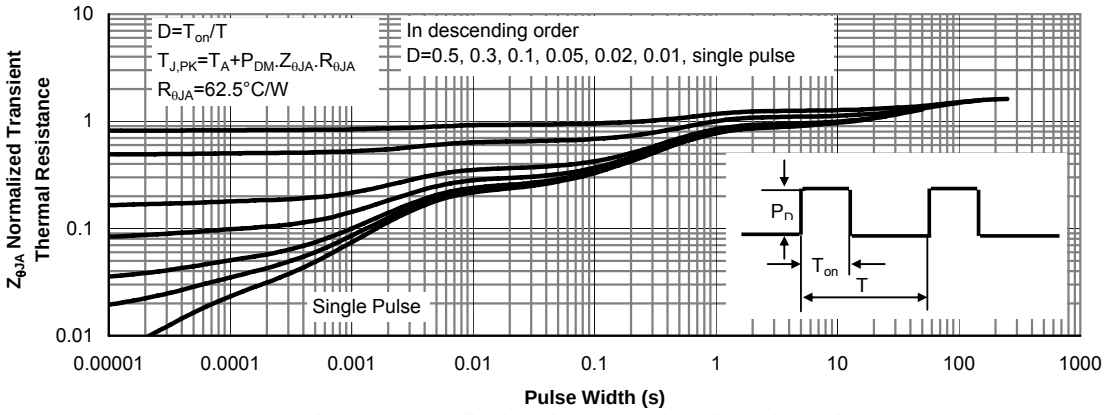


Figure 11: Normalized Maximum Transient Thermal Impedance

P-CHANNEL: Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250µA, V_{GS}=0V	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-24V, V_{GS}=0V			-1	µA
		T_J=55°C			-5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250µA	-1	-1.98	-3	V
$I_{D(ON)}$	On state drain current	V_{GS}=-4.5V, V_{DS}=-5V	-20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V, I_D=-5.4A		35	45	mΩ
		T_J=125°C		49	64	
		V_{GS}=-4.5V, I_D=-4A		58	75	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-5.4A	6	8.6		S
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.78	-1	V
I_S	Maximum Body-Diode Continuous Current				-2.8	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, f=1MHz		700	900	pF
C_{oss}	Output Capacitance			120		pF
C_{rss}	Reverse Transfer Capacitance			75		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		10	15	Ω
SWITCHING PARAMETERS						
Q_g (10V)	Total Gate Charge (10V)	V_{GS}=-10V, V_{DS}=-15V, I_D=-5.4A		14.7	19	nC
Q_g (4.5V)	Total Gate Charge (4.5V)			7.6	10	nC
Q_{gs}	Gate Source Charge			2		nC
Q_{gd}	Gate Drain Charge			3.8		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=-10V, V_{DS}=-15V, R_L=2.8Ω, R_{GEN}=3Ω		8.3		ns
t_r	Turn-On Rise Time			5		ns
$t_{D(off)}$	Turn-Off DelayTime			29		ns
t_f	Turn-Off Fall Time			14		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-5.4A, dI/dt=100A/µs		23.5	30	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-5.4A, dI/dt=100A/µs		13.4		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in ^{2} FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

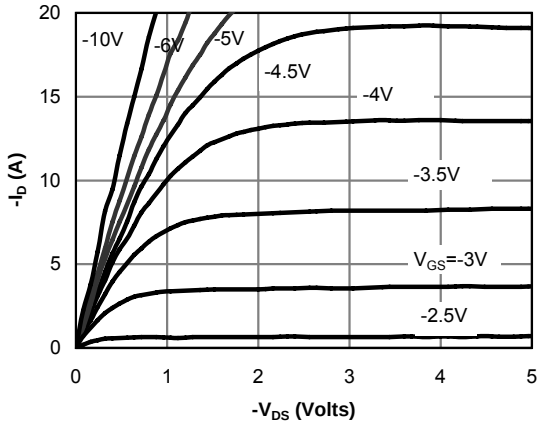
C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in ^{2} FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

Rev 0: Apr. 2006

P-CHANNEL: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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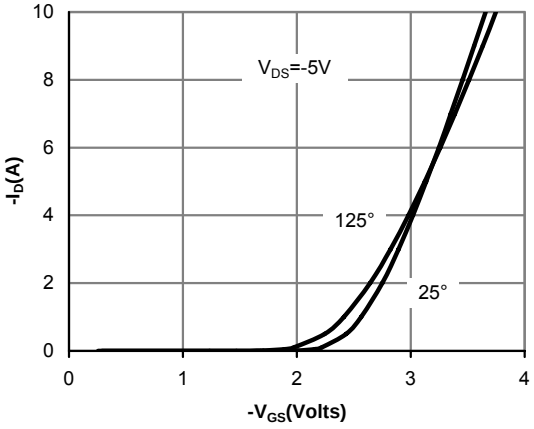
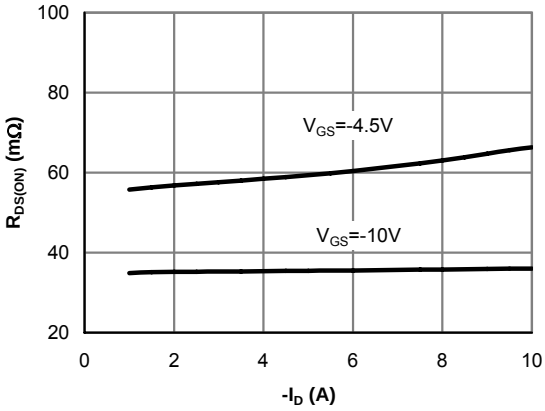


Figure 2: Transfer Characteristics



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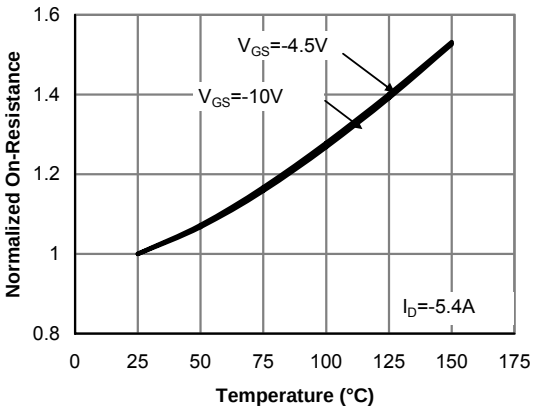

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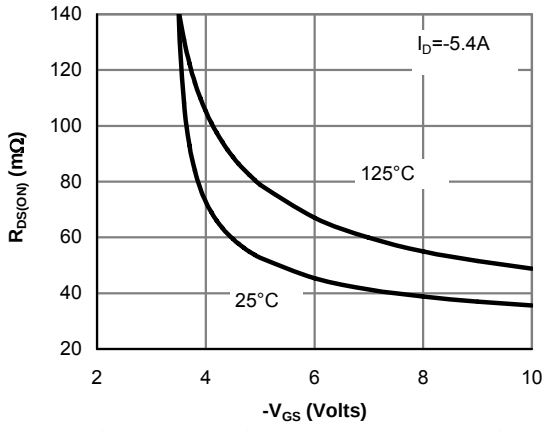

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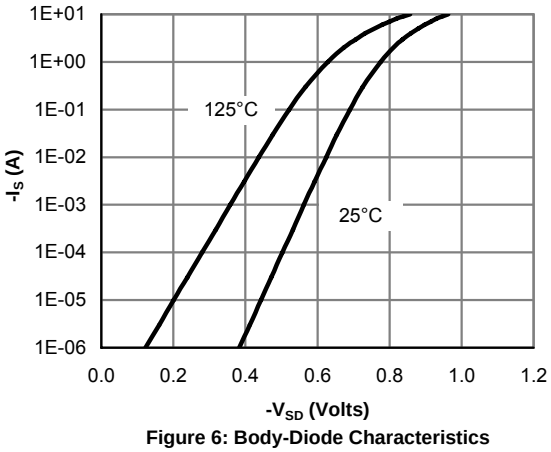

Figure 6: Body-Diode Characteristics

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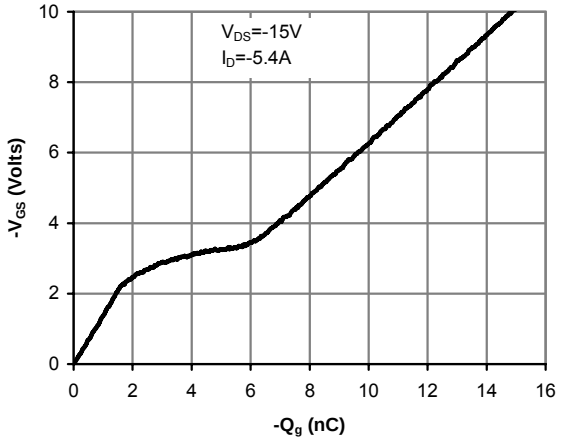

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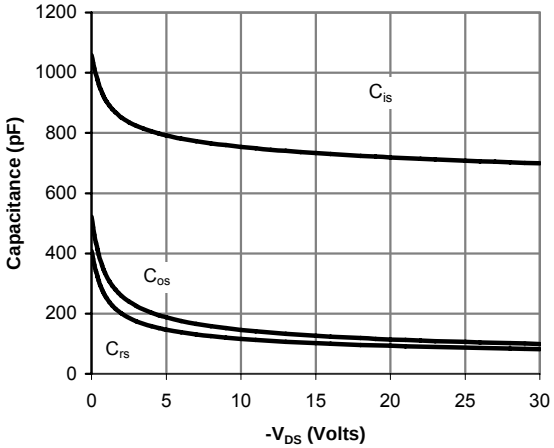

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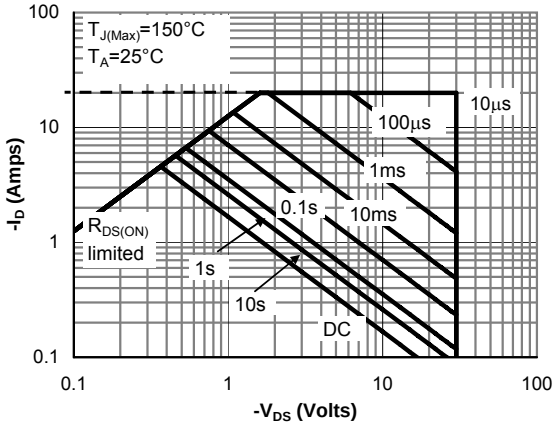

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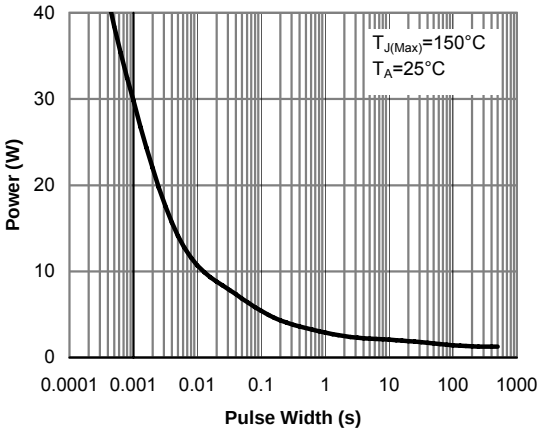

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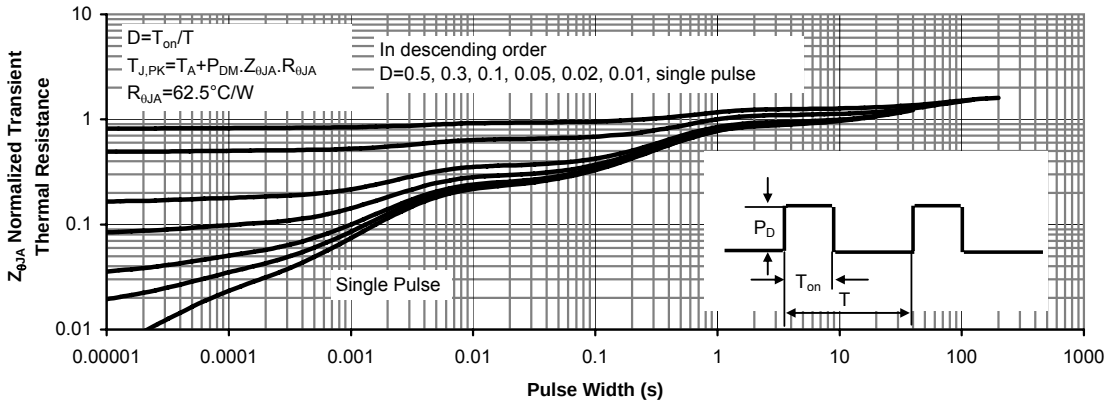

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